

MMBT3904N

NPN Plastic-
Encapsulate Transistor

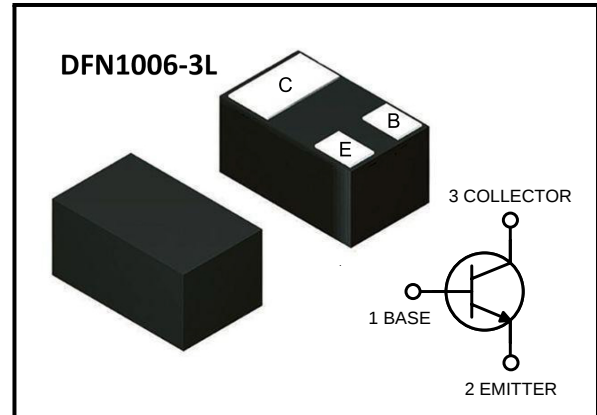
Features

- $V_{CE}=40V$
- $I_C=0.2A$
- $f_T=300MHz$ @ $V_{CE}=20V$, $I_C=10mA$, $f=100MHz$

Description

- As complementary type the PNP transistor MMBT3906N is recommended
- Epitaxial planar die construction
- DFN1006-3L Plastic Package.

Package



Marking

1N

Ordering information

Order code	Package	Marking	Base qty	Delivery mode
MMBT3904N	DFN1006-3L	1N	10K	Tape and reel

Absolute Maximum Ratings @ $T_A=25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Value	Unit
V_{CBO}	Collector-Base Voltage	60	V
V_{CEO}	Collector-Emitter Voltage	40	V
V_{EBO}	Emitter-Base Voltage	6	V
I_C	Collector Current	200	mA
P_C	Collector Power Dissipation	150	mW
$R_{\theta JA}$	Thermal Resistance From Junction to Ambient	833	$^{\circ}C/W$
T_J	Junction Temperature	150	$^{\circ}C$
T_{stg}	Storage Temperature Range	-55 to +150	$^{\circ}C$

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Electrical Characteristics (T_A=25°C, unless otherwise specified)

Symbol	Parameter	Test condition	Min.	Typ.	Max.	Unit
V _{(BR)CBO}	Collector-base breakdown voltage	I _C =10μA, I _E =0	60	—	—	V
V _{(BR)CEO}	Collector-emitter breakdown voltage	I _C =1mA, I _B =0	40	—	—	
V _{(BR)EBO}	Emitter-base breakdown voltage	I _E =10μA, I _C =0	6	—	—	
I _{CEX}	Collector cut-off current	V _{CE} =30V, V _{EB} (off)=3V	—	—	50	nA
I _{EBO}	Emitter cut-off current	V _{EB} =5V, I _C =0mA	—	—	100	nA
h _{FE(1)}	DC current gain	V _{CE} =1V, I _C =0.1mA	40	—	—	—
h _{FE(2)}		V _{CE} =1V, I _C =1mA	70	—	—	
h _{FE(3)}		V _{CE} =1V, I _C =10mA	100	—	300	
h _{FE(4)}		V _{CE} =1V, I _C =50mA	60	—	—	
V _{CE(sat)}	Collector-emitter saturation voltage	I _C =10mA, I _B =1mA	—	—	0.2	V
		I _C =50mA, I _B =5mA	—	—	0.3	
V _{BE(sat)}	Base-emitter saturation voltage	I _C =10mA, I _B =1mA	0.65	—	0.85	
		I _C =50mA, I _B =5mA	—	—	0.95	
t _d	Delay time	V _{CC} =3V, V _{BE(off)} =-0.5V, I _C =10mA, I _{B1} =1mA	—	—	35	nS
t _r	Rise time		—	—	35	
t _s	Storage time	V _{CC} =3V, I _C =10mA, I _{B1} =I _{B2} =1mA	—	—	200	
t _f	Fall time		—	—	50	
f _T	Transition frequency	V _{CE} =20V, I _C =10mA, f=100MHZ	300	—	—	MHZ
C _{ob}	Output Capacitance	V _{CB} =5V, I _E =0, f=1MHZ	—	—	4	pF
C _{ib}	Input Capacitance	V _{EB} =0.5V, I _C =0, f=1MHZ	—	—	8	pF



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Typical Performance Characteristics ($T_J = 25^\circ\text{C}$, unless otherwise noted)

Figure 1 : Static Characteristic

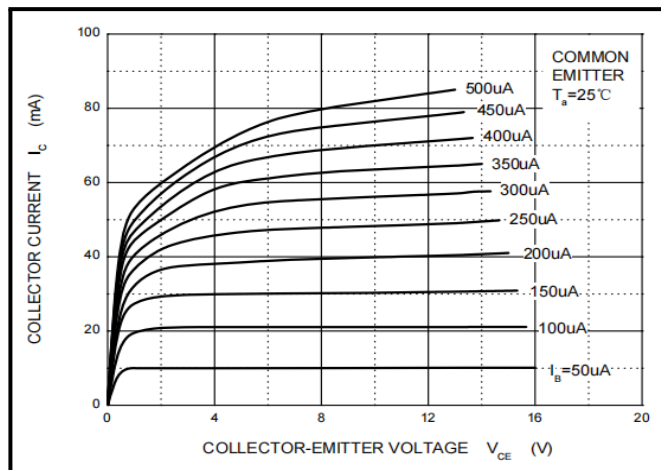


Figure 2 : $h_{FE} \sim I_C$

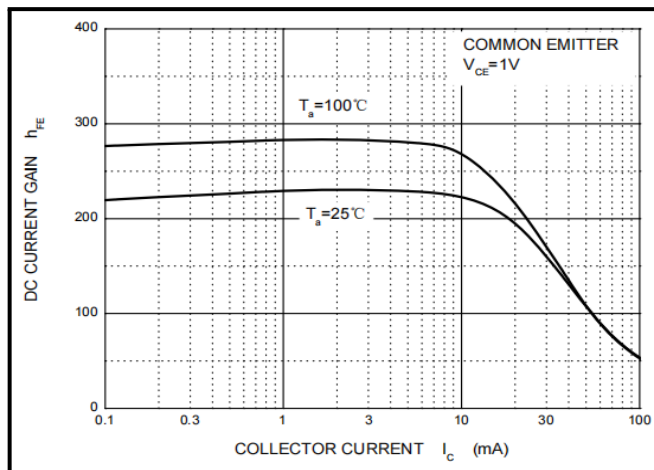


Figure 3 : $V_{CE(sat)} \sim I_C$

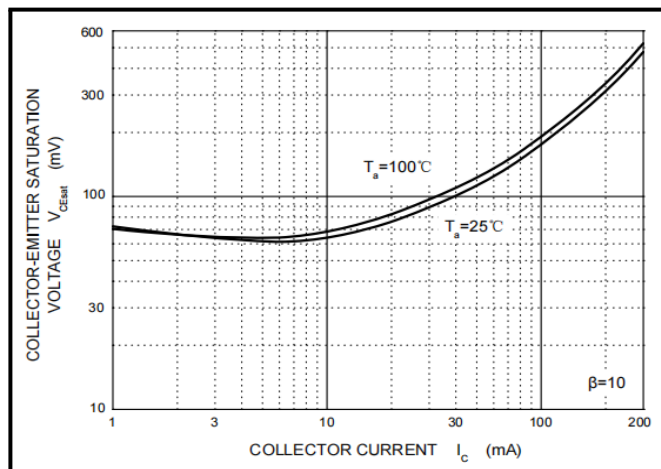
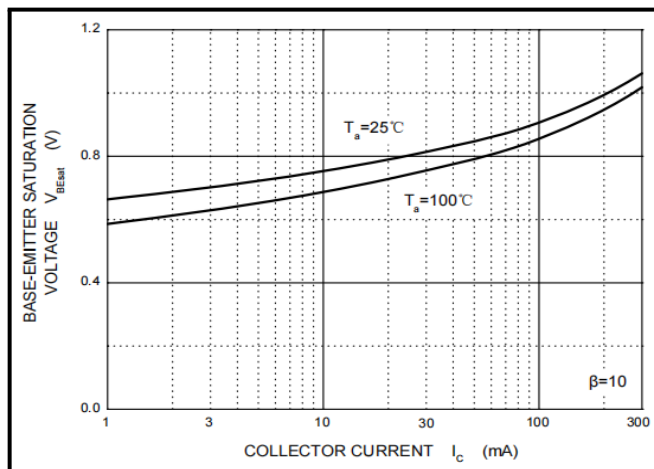


Figure 4 : $V_{BE(sat)} \sim I_C$



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Figure 5 : I_C — V_{BE}

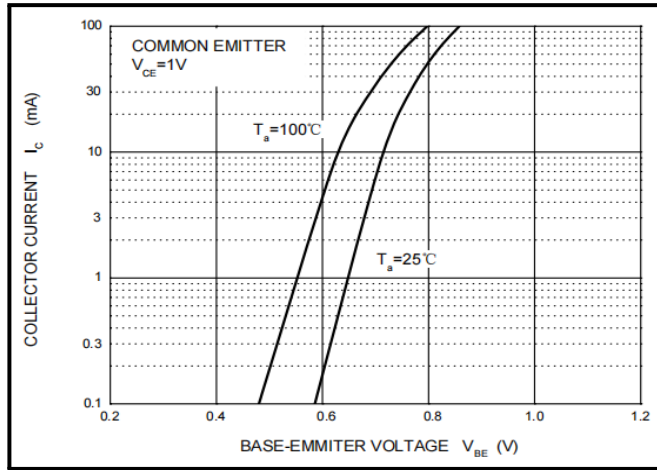


Figure 6 : C_{ob}/C_{ib} — V_{CB}/V_{EB}

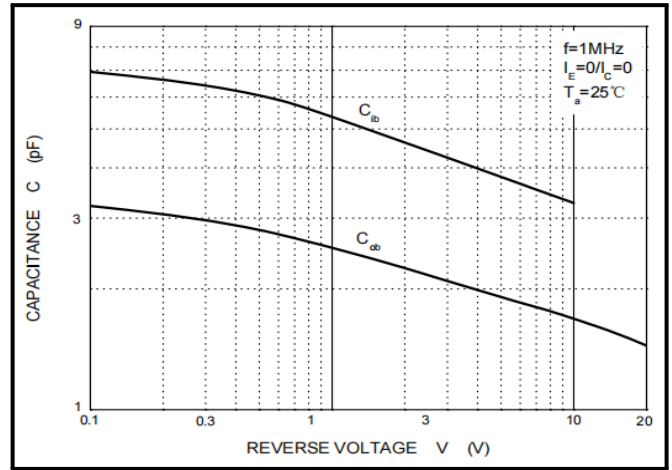


Figure 7 : f_c — I_C

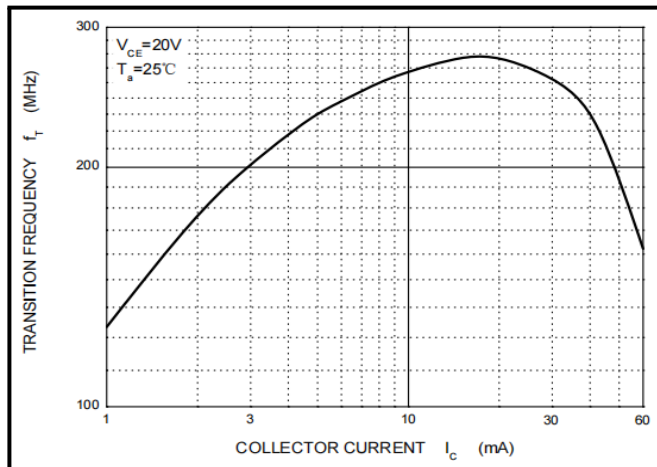
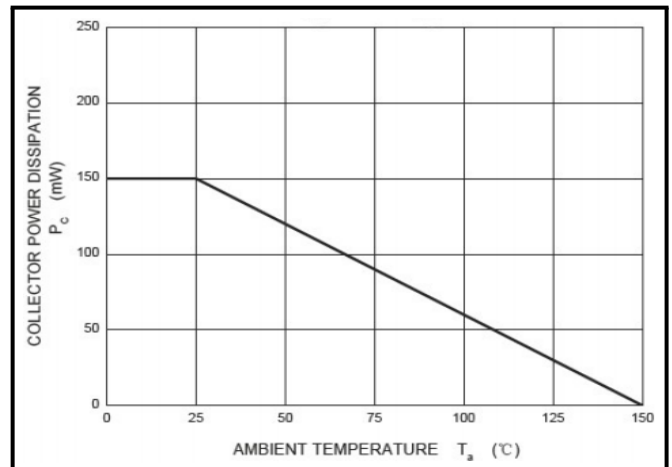


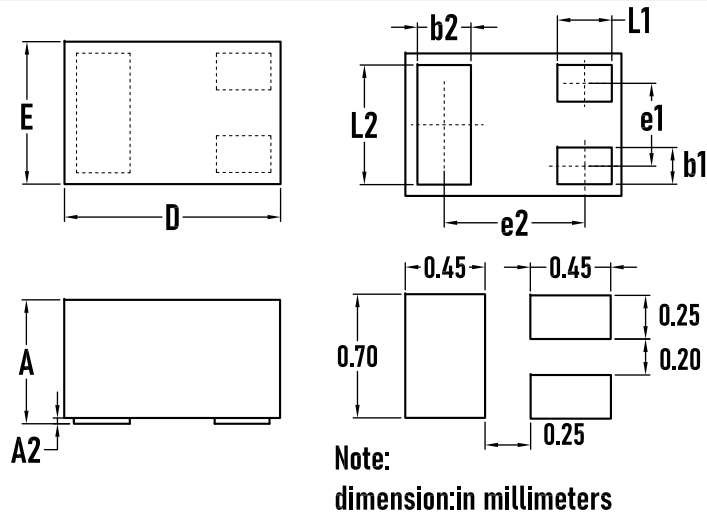
Figure 8 : P_C — T_A



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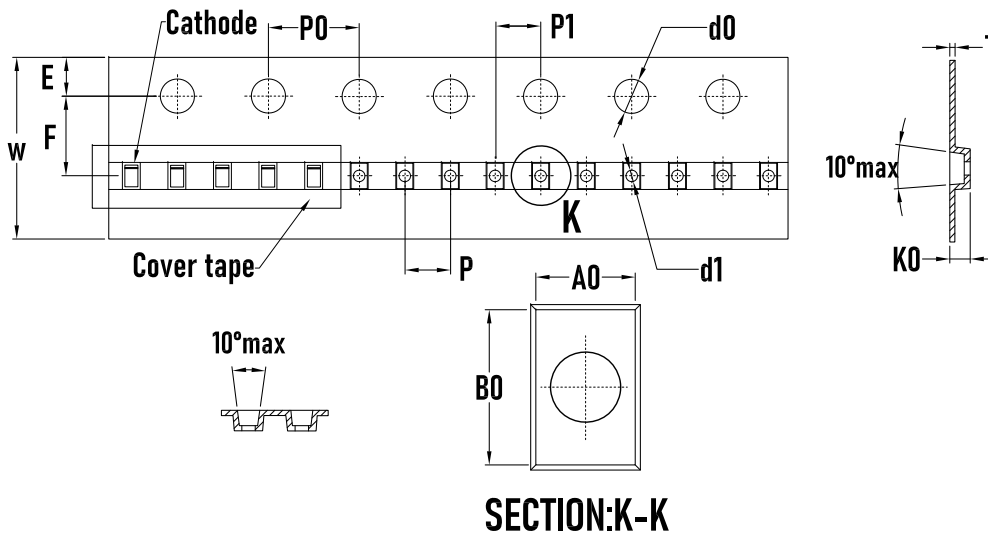
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Outline Drawing – DFN1006-3L



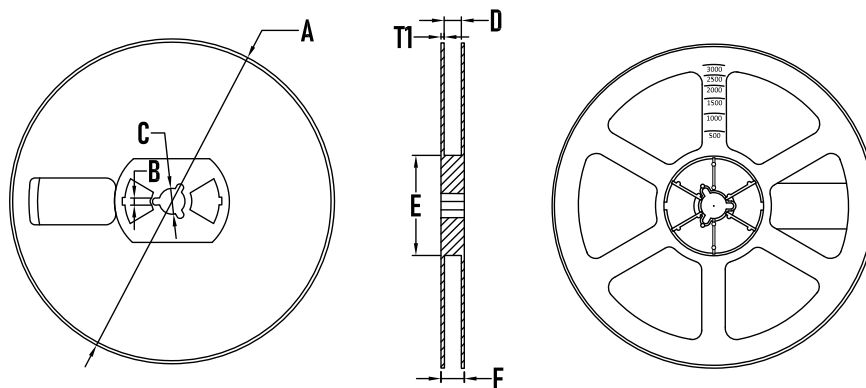
SYMBOL	MILLIMETER		
	MIN.	Typ.	MAX.
A	0.40	—	0.50
A2	0.00	—	.05
b1	0.10	0.15	0.20
b2	0.20	0.25	0.30
D	0.95	1.00	1.05
E	0.55	0.60	0.65
e1	0.350BSC		
e2	0.675BSC		
L1	0.20	0.30	0.40
L2	0.40	0.50	0.60

Packaging Tape - DFN1006



SYMBOL	MILLIMETER
A0	0.71±0.05
B0	1.11±0.05
d0	1.5 ^{+0.1} ₋₀
d1	0.50±0.05
E	1.75±0.10
F	3.50±0.05
K0	0.56±0.05
P	2.00±0.05
P0	4.00±0.10
P1	2.00±0.05
W	8.00 ^{+0.03} _{-0.01}
T	0.2±0.015

Packaging Reel



SYMBOL	MILLIMETER
A	178±1
B	3.5±0.2
C	14.3±0.2
D	9.8 ⁺² ₋₁
E	54.5±0.5
F	12.4±0.2
T1	1.0±0.2
Quantity	10000PCS

